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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : **Confirmation No. 9257**
Tetsuji TOGAWA et al. : Attorney Docket No. 2005_0993A
Serial No. 10/539,245 : Group Art Unit 3723
Filed June 16, 2005 : Examiner Maurina T. Rachuba
SUBSTRATE HOLDING MECHANISM, :
SUBSTRATE POLISHING APPARATUS
AND SUBSTRATE POLISHING METHOD

RESPONSE TO RESTRICTION REQUIREMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This is in response to the Restriction Requirement of November 21, 2006.

Applicants, by their undersigned representative, hereby elect the invention of Group II, claims 2-8 and 34.

Having made the required election, a full examination on the merits of the elected invention is hereby requested.

Respectfully submitted,

Tetsuji TOGAWA et al.

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NO. 23-0975